

IN THE CLAIMS:

1. (Currently Amended) A semiconductor integrated circuit ~~including~~ comprising:
pads, and
a plurality of wirings which are electrically connected to the pads,
wherein said wirings are ~~connected to~~ located for contacting bumps ~~of on~~ a probe card, ~~in~~
~~an area other than an area where the pads are disposed~~ when such a card is located parallel and
contiguous to said wirings, but spaced from said pads.
2. (Currently Amended) A semiconductor integrated circuit as defined in Claim 1 ~~wherein~~
comprising at least two of said wirings, both of which physically contact one of said bumps,
without ~~being in touch with~~ touching each other.
3. (Currently Amended) A semiconductor integrated circuit as defined in Claim 2 wherein
each of said wirings has at least one bent portion or angular portion for directly contacting one or
more bumps.
4. (Currently Amended) A semiconductor integrated circuit as defined in Claim 2 wherein
said wirings have electrically separable portions.